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Celanese
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HOSTAFORM® S 9364 XAP®2

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Hostaform® acetal copolymer grade S 9364 XAP®2 is a highly impact modified grade for demanding applications.
Hostaform® S 9364 XAP®2 provides a significant improvement in impact strength and flexibility over standard impact modified grades.
Hostaform® S 9364 XAP®2 exhibits exceptional low emission performance meeting or exceeding the requirements of many automotive markets. Chemical abbreviation according to ISO 1043-1: POM-HI

Product information

Resin Identification	POM-I	ISO 1043
Part Marking Code	>POM-I<	ISO 11469

Rheological properties

Melt volume-flow rate	4	cm^3/10min	ISO 1133
Temperature	190	°C	
Load	2.16	kg	
Moulding shrinkage, parallel	1.6	%	ISO 294-4, 2577
Moulding shrinkage, normal	1.5	%	ISO 294-4, 2577

Typical mechanical properties

Tensile modulus	1650	MPa	ISO 527-1/-2
Tensile stress at yield, 50mm/min	43	MPa	ISO 527-1/-2
Tensile strain at yield, 50mm/min	16	%	ISO 527-1/-2
Flexural modulus	1550	MPa	ISO 178
Flexural stress at 3.5%	42	MPa	ISO 178
Charpy impact strength, 23°C	N	kJ/m^2	ISO 179/1eU
Charpy impact strength, -30°C	N	kJ/m^2	ISO 179/1eU
Charpy notched impact strength, 23°C	21	kJ/m^2	ISO 179/1eA
Charpy notched impact strength, -30°C	11	kJ/m^2	ISO 179/1eA
Izod notched impact strength, 23°C	20	kJ/m^2	ISO 180/1A
Izod notched impact strength, -40°C	10.0	kJ/m^2	ISO 180/1A
Hardness, Rockwell, M-scale	48		ISO 2039-2
Poisson's ratio	0.42[C]		

[C]: Calculated

Thermal properties

Melting temperature, 10°C/min	165	°C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	75	°C	ISO 75-1/-2
Temperature of deflection under load, 0.45 MPa	140	°C	ISO 75-1/-2
Coefficient of linear thermal expansion (CLTE), parallel	120	E-6/K	ISO 11359-1/-2
Coefficient of linear thermal expansion (CLTE), normal	110	E-6/K	ISO 11359-1/-2

Physical/Other properties

Humidity absorption, 2mm	0.25	%	Sim. to ISO 62
Water absorption, 2mm	0.8	%	Sim. to ISO 62
Density	1360	kg/m^3	ISO 1183

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Injection

Drying Recommended	no	
Drying Temperature	100	°C
Drying Time, Dehumidified Dryer	3 - 4	h
Processing Moisture Content	≤0.2	%
Melt Temperature Optimum	190	°C
Min. melt temperature	180	°C
Max. melt temperature	200	°C
Screw tangential speed	≤0.3	m/s
Mold Temperature Optimum	65	°C
Min. mould temperature	60	°C
Max. mould temperature	70	°C
Hold pressure range	60 - 120	MPa
Back pressure	2	MPa

Characteristics

Processing	Injection Moulding, Extrusion
Delivery form	Pellets
Additives	Release agent
Special characteristics	High impact or impact modified, Low emissions

Additional information

Processing Notes

Pre-Drying

Drying is suggested to help achieve low emission performance and to counter if material has contacted moisture through improper storage and handling.

Automotive

OEM	STANDARD	ADDITIONAL INFORMATION
BAIC	Q-BJEV 01.59	
Ford	WSK-M4D618-A2	
Li Auto	Q/LiA5310020	2021 (V2)
Mercedes-Benz	DBL5404	BQF
Mercedes-Benz	DBL5410	
Renault	No Spec, Special Part Approval, See Your CE Account Manager.	
SAIC Motor	SMTC 5 310 020	
VW Group	TL 522 77	
VW Group	VW 50180	

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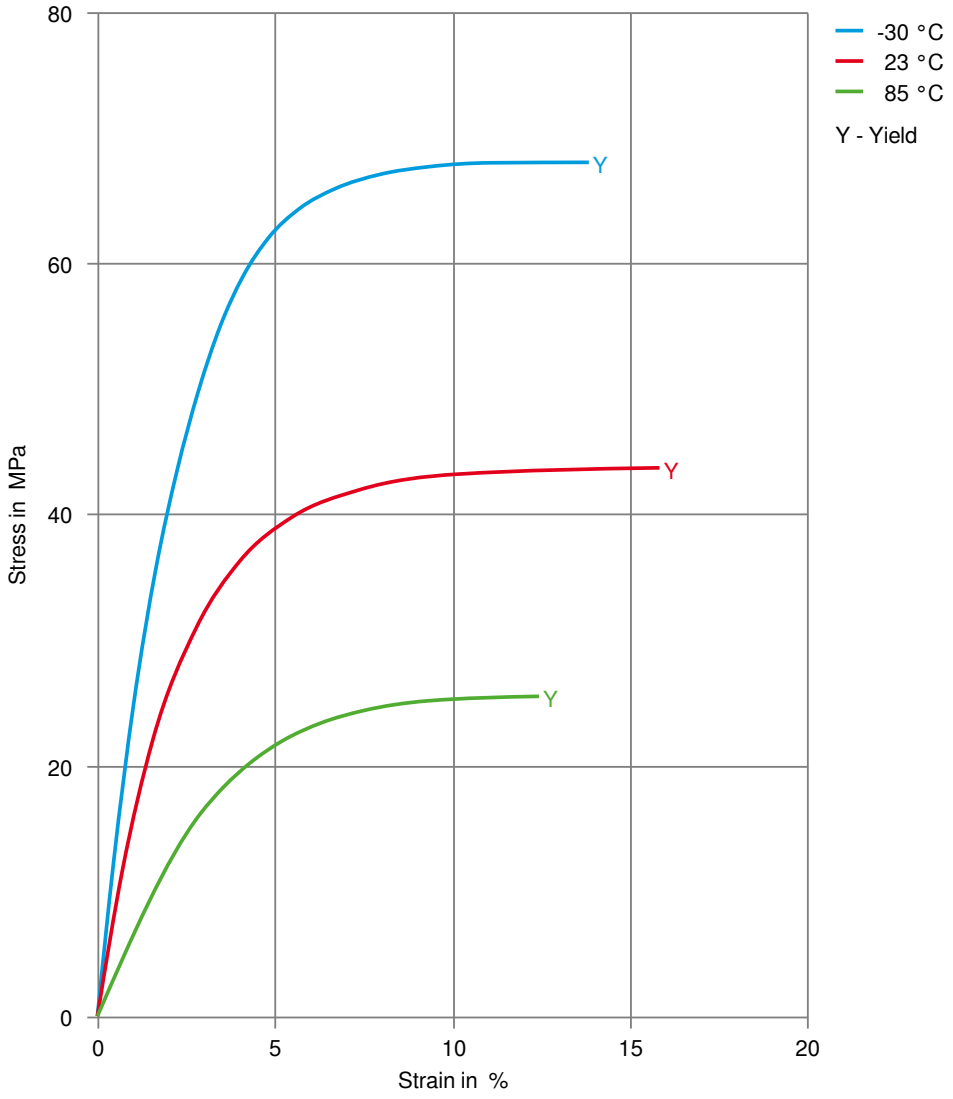
Stress-strain



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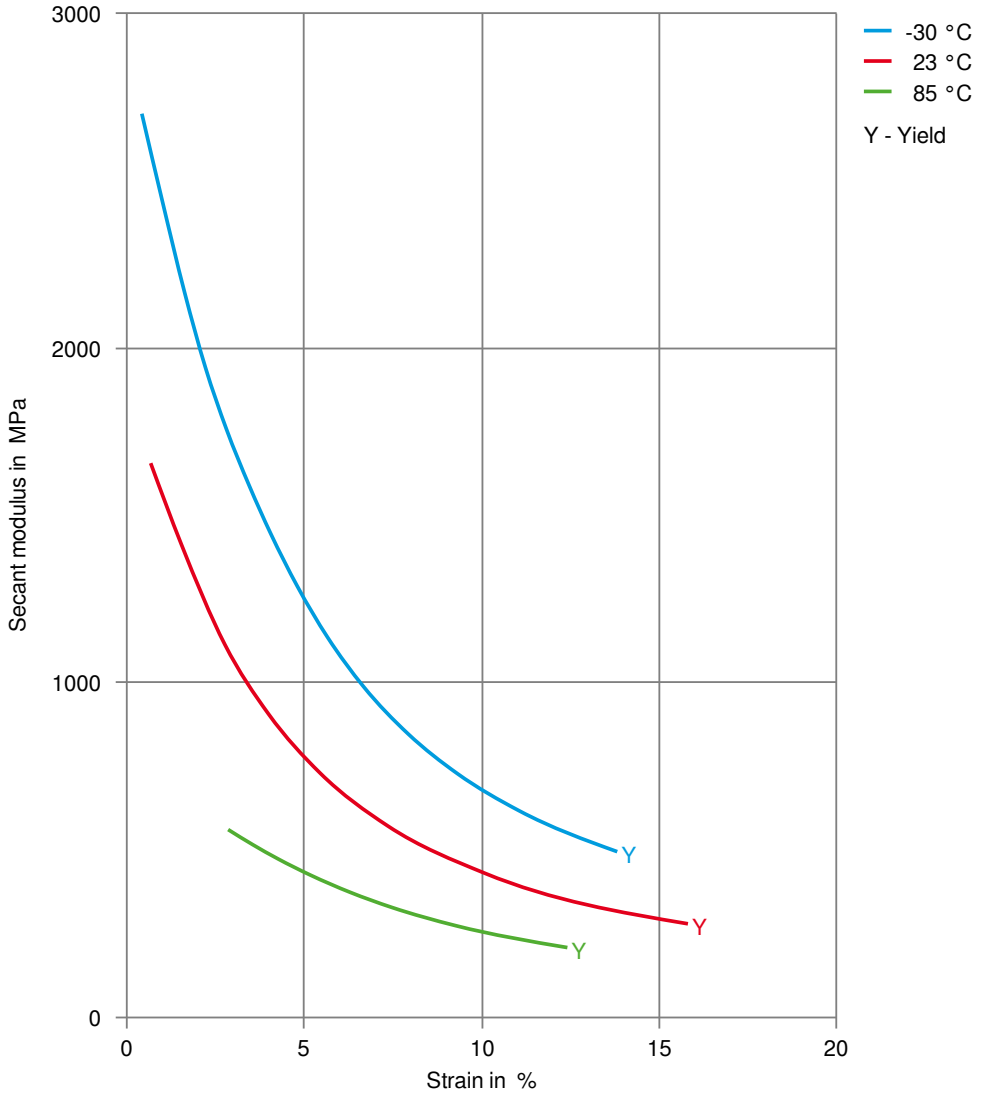
Secant modulus-strain



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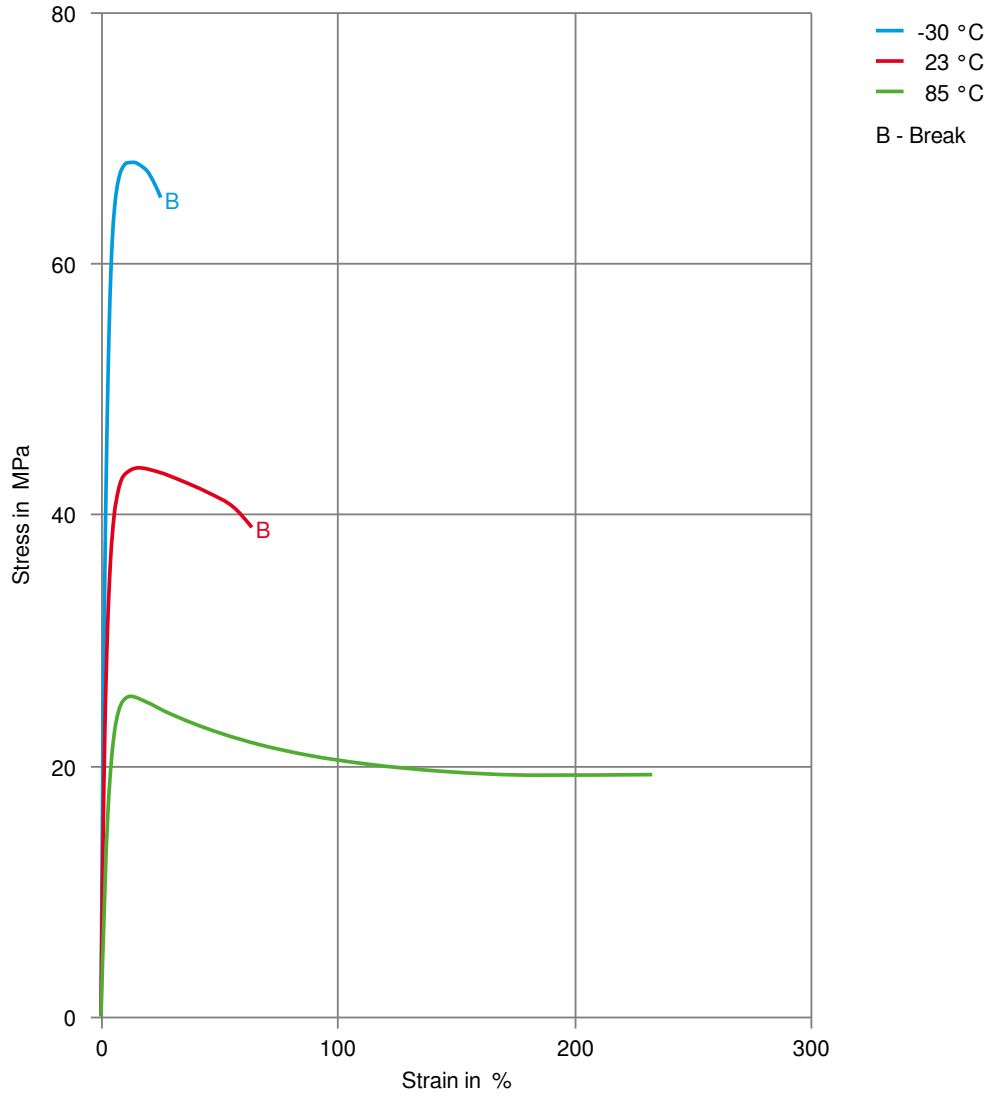
Stress-strain, 50mm/min



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Secant modulus-strain, 50mm/min